CM155 (3,000pcs/reel)



### **FEATURES:**

- Being of the ultra-miniature SMD type, and thus featuring excellent efficiency in mounting, the CM155 is ideal for application to high-density circuit boards.
- As it incorporates a heat-resisting packaged cylinder-type crystal, it features highly stable characteristics-high enough to permit reflow soldering.
- Can be mounted automatically because of the emboss taping used.
- Its low power consumption makes it ideal for application to portable equipment as well as high density, cellular phone designs.

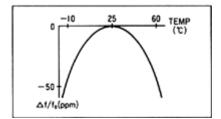
### **APPLICATIONS:**

 Permits use as a clock source for communication equipment, AV equipment, OA equipment, camera, cellular phones, pagers and measuring instruments.

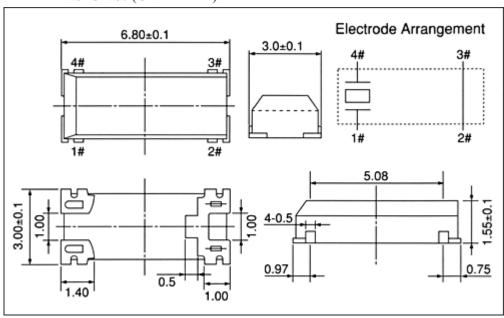
#### ■ STANDARD SPECIFICATIONS

Item		CM155	Conditions
Nominal frequency	f <sub>0</sub>	32.768kHz	
Frequency tolerance	delta f/f0	± 20ppm	Reference temperature
Frequency vs.Temperature Characteristics	delta f/f0	See drawing	-10°C to +60°C
Turnover temperature	Tm	$25^{\circ}\text{C} \pm 5^{\circ}\text{C}$	
Freq. temp. coefficient	beta	$-0.034 \pm 0.006$ ppm/°C <sub>2</sub>	
Operating temperature range	Topr	-40°C to + 85°C	
Storage temperature range	Tstg	-55°C to +125°C	
Equivalent series resistance	R <sub>1</sub>	65k ohm MAX.	Reference temperature
Load capacitance	Cl	12.5pF TYP.	Please specify
Motional capacitance	C <sub>1</sub>	0.0025pF TYP.	
Shunt capacitance	C <sub>0</sub>	1.0pF TYP.	
Capacitance ratio	gamma	400 TYP.	
Drive level	DL	1 μ W MAX.	
Insulation resistance	IR	500M ohm MIN.	$DC100V \pm 15V$
Aging (First year)	delta f/f0	± 3ppm MAX.	25°C ± 3°C
Sealing		1 x 10-2 μ Pa·m3 /s MAX.	
Shock resistance		±5ppm MAX. Drop test of 3 times on a hard board from 75cm height or shock test of 3000G x 0.3ms x 1/2sin wave x 3 directions	

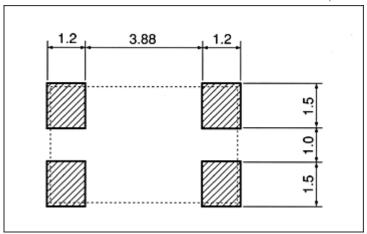
# **■ FREQUENCY vs TEMPERATURE CURVE**



# ■ DIMENSIONS: (UNIT=mm)



### ■ RECOMENDED SOLDERING PATTERN: (UNIT=mm)



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